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# **INFORMATION DISCLOSURE STATEMENT BY APPLICANT**

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Complete if Known

Application Number	10/623,679
Confirmation Number	5083
Filing Date	July 22, 2003
First Named Inventor	Koji NOZAKI et al.
Art Unit	1752
Examiner Name	Amanda C. Walke
Attorney Docket Number	030891

Sheet 1 of 1

## **U.S. PATENT DOCUMENTS**

Examiner Initials*	Cite No. <sup>1</sup>	Document Number		Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document
		Number	Kind Code <sup>2</sup> (if known)		
		US			
		US			
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## **FOREIGN PATENT DOCUMENTS**

Examiner Initials*	Cite No. <sup>1</sup>	Foreign Patent Document			Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Translation <sup>6</sup>
		Country Code <sup>3</sup>	Number <sup>4</sup>	Kind Code <sup>2</sup> (if known)			

## **NON PATENT LITERATURE DOCUMENTS**

Examiner Initials*	Cite No. <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city, and/or country where published.	Translation <sup>6</sup>
/ACW/	1	Takeo Ishibashi et al.; Advanced Micro-Lithography Process with Chemical Shrink Technology; The Japan Society of Applied Physics; Japanese Journal of Applied Physics, Vol. 40 (2001), January 15, 2001, pp. 419-425;	
/ACW/	2	Mamoru Terai et al.; Below 70-nm Contact Hole Pattern with RELACS Process on ArF Resist; Advances in Resist Technology and Processing XX, Theodore H. Fedynyshyn, Editor; Proceedings of SPIE Vol. 5039 (2003), June 12, 2003	
/ACW/	3	Mamoru Terai et al.; Newly Developed Resolution Enhancement Lithography Assisted by Chemical Shrink Process and Materials for Next-Generation Devices; The Japan Society of Applied Physics; Japanese Journal of Applied Physics, Vol. 45, No. 6B (2006), June 20, 2006, pp. 5354-5358	

Examiner Signature	/Amanda C. Walke/	Date Considered	09/29/2007
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\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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